30 V, 2 A, Low V_{CE(sat)} PNP Transistor

ON Semiconductor's e^2 PowerEdge family of low $V_{CE(sat)}$ transistors are miniature surface mount devices featuring ultra low saturation voltage ($V_{CE(sat)}$) and high current gain capability. These are designed for use in low voltage, high speed switching applications where affordable efficient energy control is important.

Typical application are DC–DC converters and power management in portable and battery powered products such as cellular and cordless phones, PDAs, computers, printers, digital cameras and MP3 players. Other applications are low voltage motor controls in mass storage products such as disc drives and tape drives. In the automotive industry they can be used in air bag deployment and in the instrument cluster. The high current gain allows e²PowerEdge devices to be driven directly from PMU's control outputs, and the Linear Gain (Beta) makes them ideal components in analog amplifiers.

- NSV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS $(T_A = 25^{\circ}C)$

Rating	Symbol	Max	Unit
Collector-Emitter Voltage	V_{CEO}	-30	Vdc
Collector-Base Voltage	V _{CBO}	-50	Vdc
Emitter-Base Voltage	V_{EBO}	-5.0	Vdc
Collector Current - Continuous	I _C	-1.0	Α
Collector Current – Peak	I _{CM}	-2.0	Α

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit	
Total Device Dissipation T _A = 25°C	P _D (Note 1)	310	mW	
Derate above 25°C		2.5	mW/°C	
Thermal Resistance, Junction to Ambient	R _{θJA} (Note 1)	403	°C/W	
Total Device Dissipation T _A = 25°C Derate above 25°C	P _D (Note 2)	710 5.7	mW mW/°C	
Derate above 25 C		5.7		
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$ (Note 2)	176	°C/W	
Total Device Dissipation (Single Pulse < 10 sec.)	P _{Dsingle} (Note 3)	575	mW	
Junction and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

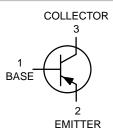
- 1. FR-4 @ Minimum Pad.
- 2. FR-4 @ 1.0 X 1.0 inch Pad.
- 3. Refer to Figure 8.



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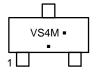
$\begin{array}{c} 30 \text{ VOLTS} \\ 2.0 \text{ AMPS} \\ \text{PNP LOW V}_{\text{CE(sat)}} \text{ TRANSISTOR} \\ \text{EQUIVALENT R}_{\text{DS(on)}} \text{ 200 m} \Omega \end{array}$





SOT-23 (TO-236) CASE 318 STYLE 6

MARKING DIAGRAM



VS4 = Specific Device Code

M = Date Code*

■ = Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or overbar may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping [†]		
NSS30100LT1G, NSV30100LT1G	SOT-23 (Pb-Free)	3000/Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

ELECTRICAL CHARACTERISTICS ($T_A = 25$ °C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector – Emitter Breakdown Voltage (I _C = -10 mAdc, I _B = 0)	V _{(BR)CEO}	-30	_	Vdc
Collector – Base Breakdown Voltage (I _C = -0.1 mAdc, I _E = 0)	V _{(BR)CBO}	-50	_	Vdc
Emitter-Base Breakdown Voltage (I _E = -0.1 mAdc, I _C = 0)	V _{(BR)EBO}	-5.0	_	Vdc
Collector Cutoff Current (V _{CB} = -30 Vdc, I _E = 0)	I _{CBO}	-	-0.1	μAdc
Collector–Emitter Cutoff Current (V _{CES} = -30 Vdc)	I _{CES}	_	-0.1	μAdc
Emitter Cutoff Current (V _{EB} = -4.0 Vdc)	I _{EBO}	ı	-0.1	μAdc
ON CHARACTERISTICS				
DC Current Gain (Note 4) (Figure 1) $ (I_C = -1.0 \text{ mA}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -500 \text{ mA}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = -1.0 \text{ A}, V_{CE} = -2.0 \text{ V}) $ $ (I_C = 2.0 \text{ A}, V_{CE} = -2.0 \text{ V}) $	h _{FE}	100 100 80 40	- 300 - -	
Collector – Emitter Saturation Voltage (Note 4) (Figure 3) $ \begin{aligned} &(I_C=-0.5 \text{ A}, I_B=-0.05 \text{ A}) \\ &(I_C=-1.0 \text{ A}, I_B=0.1 \text{ A}) \\ &(I_C=-2.0 \text{ A}, I_B=-0.2 \text{ A}) \end{aligned} $	V _{CE(sat)}	- - -	-0.25 -0.30 -0.65	V
Base – Emitter Saturation Voltage (Note 4) (Figure 2) (I _C = -1.0 A, I _B = -0.1 A)	V _{BE(sat)}	-	-1.2	V
Base – Emitter Turn–on Voltage (Note 4) (I _C = -1.0 A, V _{CE} = -2.0 V)	V _{BE(on)}	-	-1.1	V
Cutoff Frequency ($I_C = -100 \text{ mA}$, $V_{CE} = -5.0 \text{ V}$, $f = 100 \text{ MHz}$)	f _T	100	-	MHz
Output Capacitance (f = 1.0 MHz)	Cobo	_	15	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulsed Condition: Pulse Width = 300 msec, Duty Cycle ≤ 2%.

TYPICAL CHARACTERISTICS

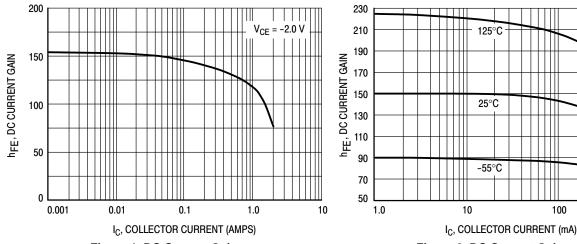


Figure 1. DC Current Gain versus Collector Current

Figure 2. DC Current Gain versus Collector Current

1000

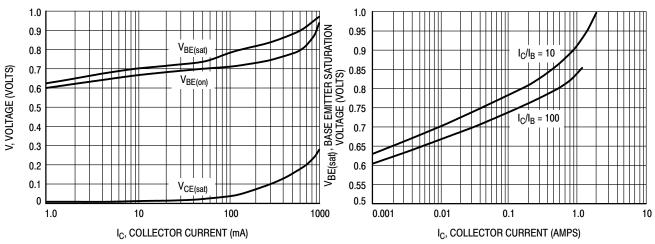


Figure 3. "On" Voltages

Figure 4. Base Emitter Saturation Voltage versus Collector Current

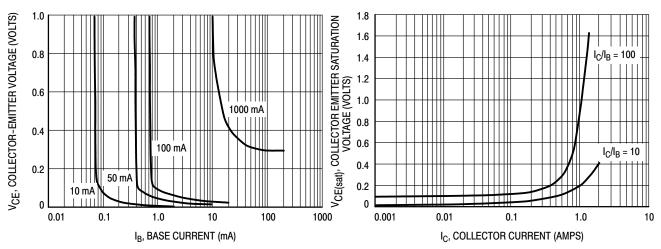


Figure 5. Collector Emitter Saturation Voltage versus Base Current

Figure 6. Collector Emitter Saturation Voltage versus Collector Current

TYPICAL CHARACTERISTICS

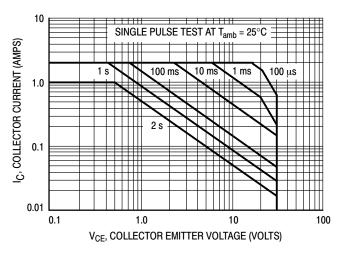


Figure 7. Safe Operating Area

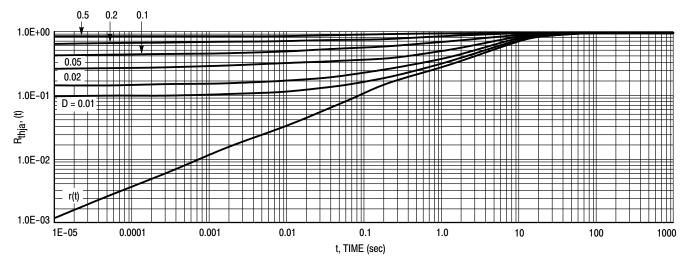


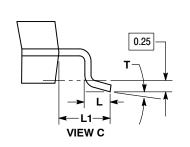
Figure 8. Normalized Thermal Response

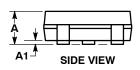


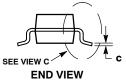
SOT-23 (TO-236) CASE 318-08 **ISSUE AS**

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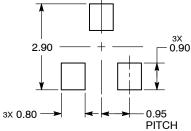
SCALE 4:1 D - 3X b **TOP VIEW**







RECOMMENDED SOLDERING FOOTPRINT



DIMENSIONS: MILLIMETERS

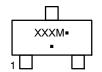
3. ANODE

NOTES:

- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH.
 MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF THE BASE MATERIAL
- 4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.89	1.00	1.11	0.035	0.039	0.044
A1	0.01	0.06	0.10	0.000	0.002	0.004
b	0.37	0.44	0.50	0.015	0.017	0.020
С	0.08	0.14	0.20	0.003	0.006	0.008
D	2.80	2.90	3.04	0.110	0.114	0.120
E	1.20	1.30	1.40	0.047	0.051	0.055
е	1.78	1.90	2.04	0.070	0.075	0.080
L	0.30	0.43	0.55	0.012	0.017	0.022
L1	0.35	0.54	0.69	0.014	0.021	0.027
HE	2.10	2.40	2.64	0.083	0.094	0.104
Т	O٥		10°	O۰		10°

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code

= Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

STYLE 1 THRU 5: CANCELLED	STYLE 6: PIN 1. BASE 2. EMITTER 3. COLLECTOR	STYLE 7: PIN 1. EMITTER 2. BASE 3. COLLECTOR	STYLE 8: PIN 1. ANODE 2. NO CONNECTION 3. CATHODE	ı	
STYLE 9:	STYLE 10:	STYLE 11: PIN 1. ANODE 2. CATHODE 3. CATHODE-ANODE	STYLE 12:	STYLE 13:	STYLE 14:
PIN 1. ANODE	PIN 1. DRAIN		PIN 1. CATHODE	PIN 1. SOURCE	PIN 1. CATHODE
2. ANODE	2. SOURCE		2. CATHODE	2. DRAIN	2. GATE
3. CATHODE	3. GATE		3. ANODE	3. GATE	3. ANODE
STYLE 15:	STYLE 16:	STYLE 17: PIN 1. NO CONNECTION 2. ANODE 3. CATHODE	STYLE 18:	STYLE 19:	STYLE 20:
PIN 1. GATE	PIN 1. ANODE		PIN 1. NO CONNECTION	I PIN 1. CATHODE	PIN 1. CATHODE
2. CATHODE	2. CATHODE		2. CATHODE	2. ANODE	2. ANODE
3. ANODE	3. CATHODE		3. ANODE	3. CATHODE-ANODE	3. GATE
STYLE 21:	STYLE 22:	STYLE 23:	STYLE 24:	STYLE 25:	STYLE 26:
PIN 1. GATE	PIN 1. RETURN	PIN 1. ANODE	PIN 1. GATE	PIN 1. ANODE	PIN 1. CATHODE
2. SOURCE	2. OUTPUT	2. ANODE	2. DRAIN	2. CATHODE	2. ANODE
3. DRAIN	3. INPUT	3. CATHODE	3. SOURCE	3. GATE	3. NO CONNECTION
STYLE 27: PIN 1. CATHODE 2. CATHODE	STYLE 28: PIN 1. ANODE 2. ANODE				

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3. CATHODE

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